

# IFX Day 2010

Campeon – June 24, 2010

Weng Kuan Tan  
Division President

Wireless Solutions (WLS)



# Infineon Is Growing Share and Becoming Top-3 Player Now

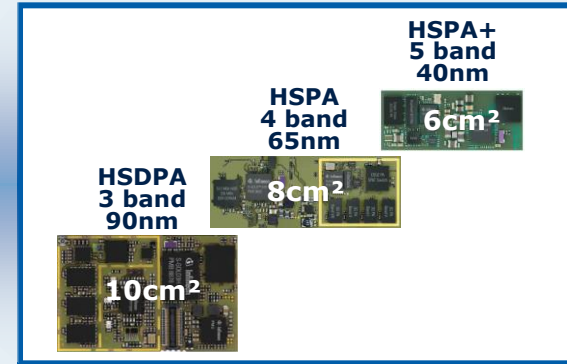


## Infineon Wireless market position

3G

WCDMA/HSxPA Baseband suppliers	Rank		Market share	
	2008	2009	2008	2009
Texas Instruments*	1	1	35.6%	30.4%
Qualcomm	2	2	32.0%	29.8%
<b>Infineon</b>	<b>4</b>	<b>3</b>	<b>7.2%</b>	<b>14.1%</b>
ST-Ericsson	3	4	15.1%	14.1%
Broadcom	5	5	2.4%	2.9%
Other			7.7%	8.7%

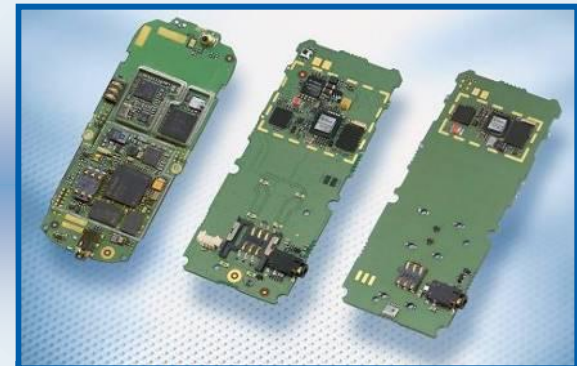
### Slim modems



2G

GSM/GPRS/EDGE Baseband suppliers	Rank		Market share	
	2008	2009	2008	2009
Texas Instruments*	1	1	40.7%	33.7%
Mediatek	2	2	23.3%	32.7%
<b>Infineon</b>	<b>4</b>	<b>3</b>	<b>12.4%</b>	<b>13.4%</b>
ST-Ericsson	3	4	13.4%	11.7%
Broadcom	9	5	0.2%	3.7%
Other			10.0%	4.8%

### SoC platforms

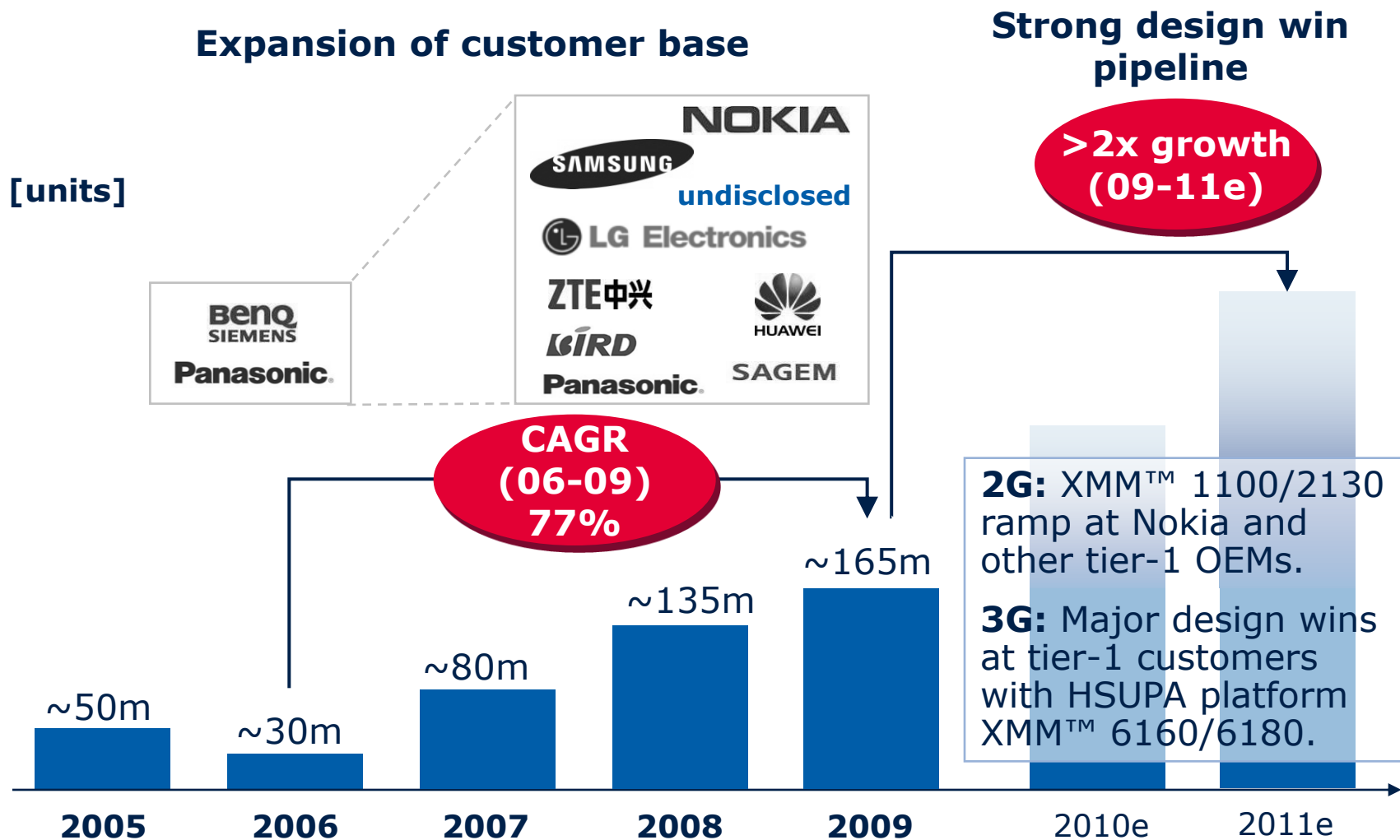


\*TI expects substantially all of its baseband revenue, which was \$1.73bn in 2009, to cease by the end of 2012.

Source: Strategy Analytics, market shares are unit based

# Major Design Wins to Drive Further Growth

## Key growth drivers of Infineon platform shipments



# Strong Ramps at Nokia in 2010 and 2011

## Nokia mobile phones based on Infineon platforms

Series 40



Dual-SIMs

Nokia C1-01    Nokia C1-02    Nokia C2-00

**Based on XMM™ 2130**

Series 30

One model for one market (India)

Multiple models for the global market: China, India, MEA, Eurasia, SEAP, ...



Nokia 1202



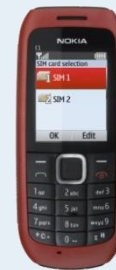
Nokia 1280



Nokia 1616



Nokia 1800



Nokia C1-00

Dual-SIMs

**Based on XMM™ 1010**

**Based on XMM™ 1100**

**2008**

**1H 2010**

**2H 2010**

# Leading Smartphone Customer Base

## Selected smartphone models using Infineon platform / RF



**Samsung  
Galaxy S**

HSUPA platform  
XMM™ 6160



**Undisclosed  
customer**

HSUPA platform  
XMM™ 6160



**Another undisclosed  
tier-1 customer**

HSPA+ platform  
XMM™ 6260



**RIM BlackBerry  
Bold 9700**

HSUPA RF  
SMARTi 3GE2



**Motorola  
Milestone**

HSUPA RF  
SMARTi UE+



# Focus on Fastest Growing Market Segments Smartphones and Connected Devices

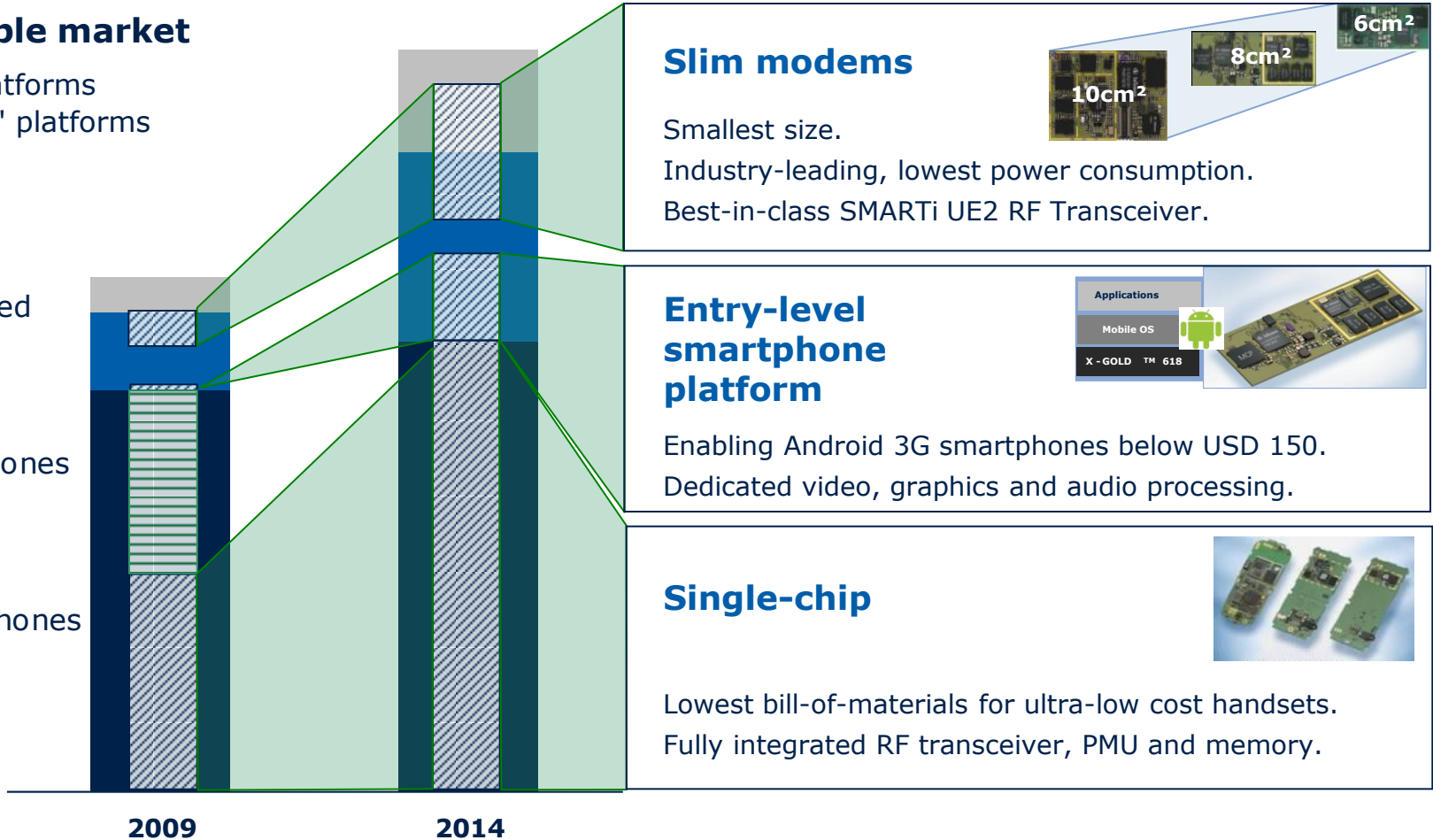


## Applications and roadmap focus

### Addressable market

-  New platforms
-  "Legacy" platforms

-  Connected devices
-  Smartphones
-  Mobile Phones



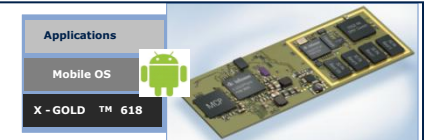
### Slim modems

Smallest size.  
Industry-leading, lowest power consumption.  
Best-in-class SMARTi UE2 RF Transceiver.



### Entry-level smartphone platform

Enabling Android 3G smartphones below USD 150.  
Dedicated video, graphics and audio processing.



### Single-chip

Lowest bill-of-materials for ultra-low cost handsets.  
Fully integrated RF transceiver, PMU and memory.



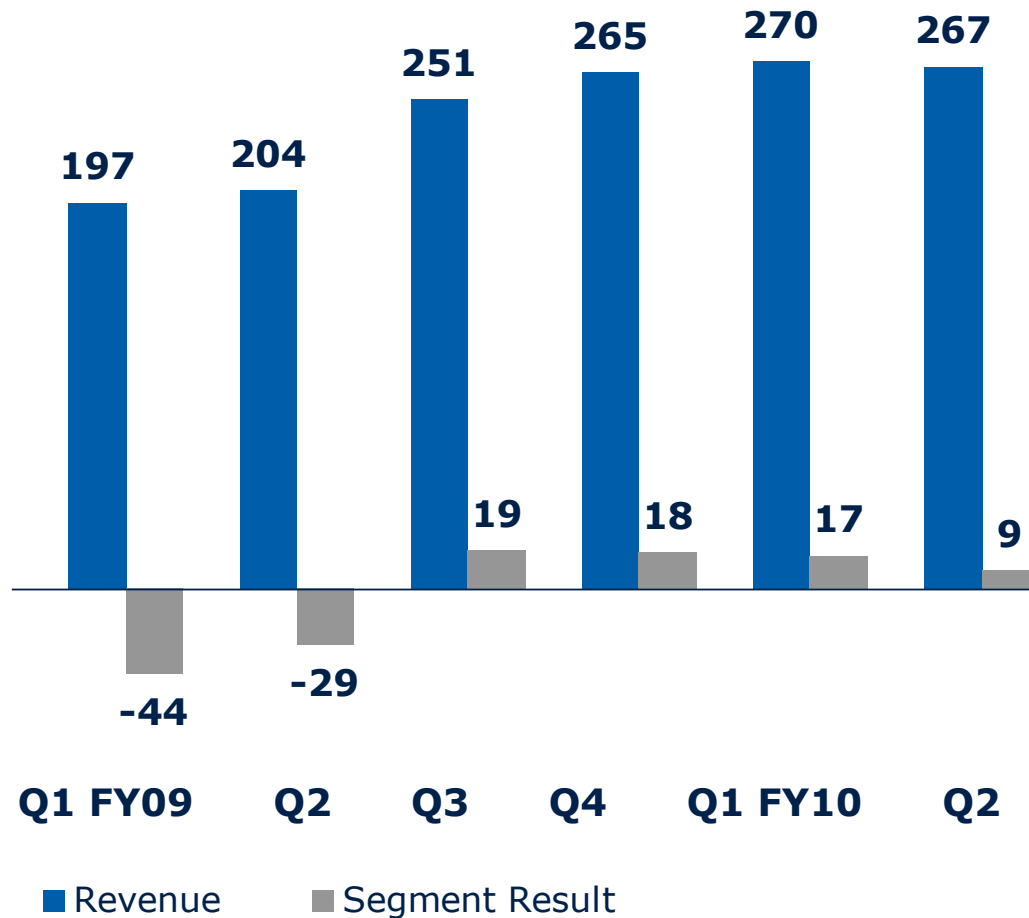
Source: Strategy Analytics, September 2009

# Profitability to Increase Further Through Growth, Fabless Transition and R&D Efficiency



## Financial performance

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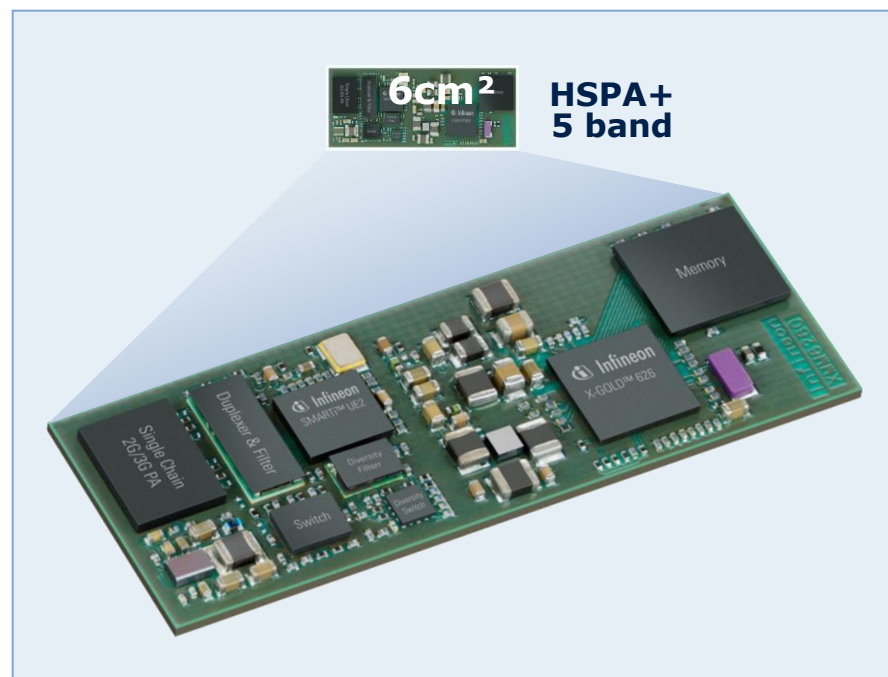


### Key levers for increased profitability:

- Grow scale further through 2010 and 2011 by ramping design wins (CY 2009 revenue was \$1.4bn).
- Leverage fabless transition and new technologies for gross margin improvement.
- Execute on R&D efficiency program to address challenges from increasing engagements at customers and growing product portfolio.

# Summary

- No. 2 in 2G and 3G platforms (excl. TI baseband ASICs).
- Poised for strong share gains in 2G and 3G, driven by:
  - strong design win pipeline,
  - leading customer base,
  - roadmap focused on fastest growing market segments.
- Higher scale, as well as gross margin and R&D measures are expected to increase profitability further.







# ENERGY EFFICIENCY COMMUNICATIONS SECURITY

Innovative semiconductor solutions for energy efficiency, communications and security.



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